

## Full Material Declaration for attached parts list

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## Diotec Semiconductor AG

DUNS number: 330866844

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Declarations authorised by

Udo Steinebrunner, Product Manager, -

Declaration effective from: 01 January 2009 [Approved: 20 May 2025 09:15 GMT]

Individual materials in the part			Individual substances in each material		
Use/Location	Material Group	Max mass %	Substance	CAS Number	Max mass %
Chip (die)	Other inorganic materials	0.3%	<b>Nickel</b> REACH Article 67 Exemption	7440-02-0	1%
			Gold	7440-57-5	11.5%
			Polydimethyl siloxane	63148-62-9	25%
			Silicon	7440-21-3	62.5%
			Silver	7440-22-4	2.5%
Die attach	Lead and Lead alloys	0.2%	Tin	7440-31-5	5%
			<b>Lead</b> EU RoHS Exemption 7(a) Exempt from other regulatory requirements Exempt from other regulatory requirements	7439-92-1	92.5%
Encapsulation	EP (Epoxy resin)	22.1%	Carbon black	1333-86-4	0.3%
			ALUMINUM(III) HYDROXIDE	21645-51-2	1.79%
			Phenol, polymer with formaldehyde	9003-35-4	7.61%
Leadfinish	Tin plating	2.3%	Formaldehyde, polymer with (chloromethyl)oxirane and 2-methylphenol	29690-82-2	20%
			<b>Quartz silica</b> Exempt from other regulatory requirements	14808-60-7	70.3%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	75.1%	Tin	7440-31-5	100%
			Copper	7440-50-8	100%

**Attached parts list**

Part number	Part name
D 5.4x7.5 (DCN) HF	Diode axial